

SURFACE MOUNT DISPLAY

KPDA02-112 WHITE

Features

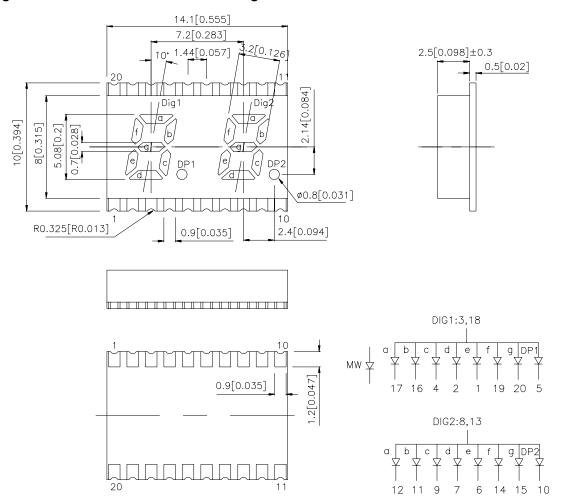
- •0.2 INCH DIGIT HEIGHT.
- •LOW CURRENT OPERATION.
- •EXCELLENT CHARACTER APPEARANCE.
- •I.C. COMPATIBLE.
- •MECHANICALLY RUGGED.
- •GRAY FACE, WHITE SEGMENT.
- •PACKAGE: 600PCS/REEL.

Description

The source color devices are made with GaN on SiC Light Emitting Diode.

Static electricity and surge damage the LEDS. It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs. All devices, equipment and machinery must be electrically grounded.

Package Dimensions& Internal Circuit Diagram



Notes:

- 1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted.
- 2. Specifications are subject to change whitout notice.

SPEC NO: DSAB0174 APPROVED: J. Lu REV NO: V.4 CHECKED :Joe Lee DATE: NOV/11/2002 DRAWN: L.ZHANG PAGE: 1 OF 4



Selection Guide

Part No.	Dice	Lens Type	lv (ucd) @ 20 mA		Description
			Min.	Тур.	
KPDA02-112	WHITE (GaN)	WHITE DIFFUSED	1600	8700	Common Anode, Rt. Hand Decimal

Electrical / Optical Characteristics at T_A=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
VF	Forward Voltage	White	3.8	4.5	٧	IF=20mA
IR	Reverse Current	White	-	10	uA	V _R = 5V
Х	- Chromaticity Coordinates	White	0.33	-	-	-
Y			0.34	-	-	-
С	Capacitance	White	100		pF	V _F =0V, f =1MHz

Absolute Maximum Ratings at T_A=25°C

Parameter	White	Units
Power dissipation	105	mW
DC Forward Current	30	mA
Forward Current (Peak) [1]	150	mA
Reverse Voltage	5	V
Operating Temperature	ing Temperature -40°C To +85°C	
Storage Temperature	-40°C To +85°C	

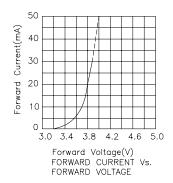
Note

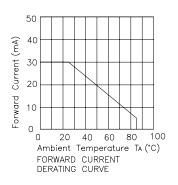
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

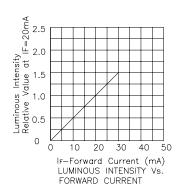
SPEC NO: DSAB0174 REV NO: V.4 DATE: NOV/11/2002 PAGE: 2 OF 4
APPROVED: J. Lu CHECKED: Joe Lee DRAWN: L.ZHANG

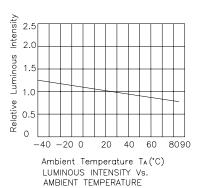
Kingbright

White KPDA02-112





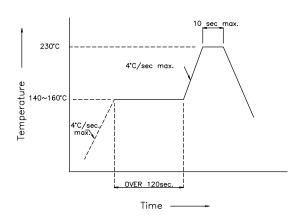




PAGE: 3 OF 4

KPDA02-112 SMT Reflow Soldering Instruction

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.

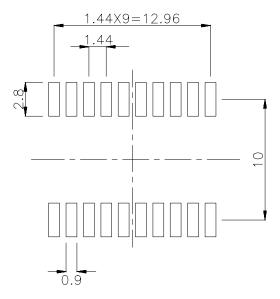


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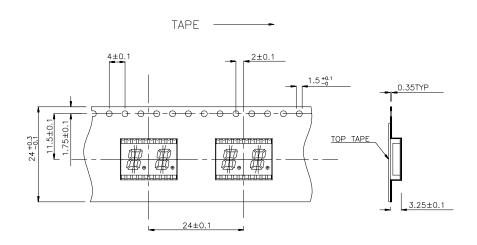


Recommended Soldering Pattern

(Units:mm)



Tape Specification (Units : mm)



PAGE: 4 OF 4

REV NO: V.4 SPEC NO: DSAB0174 DATE: NOV/11/2002 **CHECKED**: Joe Lee APPROVED: J. Lu **DRAWN: L.ZHANG**